SPAR - BRAMPTON (SSS)
9445 AIRPORT RD

BRAMPTON ONTARIO L6S4J3

Critical Items List

SRMS

CIL Ref#: 3121

Revision: 0 FMEA Rev: 1

System: SRMS

Subsystem: ELECTRICAL SUB-SYSTEM

Assembly Desc: Servo Power Amplifier

Part Number(s): 51140F1177-3 51140F1177-5

Item:		
Function:	Motor Drive Amplifier Assembly	Provides motor voltage based on demand from tachometer electronics. Commutates the motor drive voltage. Provides hardware current limiting, brake drive, direct drive functions and enables backup drive. Provides BITE circuits and BITE verification for MDA.
	Filter Board Assembly	Filters 28V to SPA. Filters secondary voltages to position encoder, commutator and tachometer SCU. Provides backup relay to switch motor to backup drive.

Failure Mode: Loss of or Sluggish Backup Drive.

	H/W	Func.	Screen	Failures
Criticality:	2	1R		

Mission Phase: Orbit

Cause(s):	
Filter Board Assembly	One or more backup relay contacts failed to normally closed position.
Motor Drive Amplifier Assembly	Brake permanently ON in backup.
	Loss of backup commutator enable.
	Loss of output FET isolation in backup mode.

Failure effect on next unit/end item:

In Backup, joint brake may not be lifted, joint drive may be sluggish or joint will not drive. BDA fuse may be blown or BDA may shut down resulting in loss of Backup Drive for all joints. If fuse not blown BDA may be able to overdrive the brake.

Worst Case: Loss of Backup Drive Mode.

Redundant Paths: Computer Supported modes.
Direct Drive.

Retention Rationale

Design:

Relays are hermetically sealed types, conforming to MIL-R-39016 as dictated by the design application. In addition, all relays are screened to NASA ST-R-0001 requirements. Contact current and voltage stresses are reduced in accordance wih the derating rquirements of SPAR-RMS-PA.003. In the packaging design, emphasis has been placed upon relay mounting to ensure good heat transfer and immunity from vibration.

Discrete semiconductor devices are specified to at least the TX level of MIL-S-19500. Samples of all procured lots/date codes are subjected to destructive physical analysis (DPA) to verify the integrity of the manufacturing processes. Particle Impact Noise Detection (PIND) screening is performed on microcircuits, transistor and diodes that are mounted in a package with an internal cavity construction. The purpose of the test is to detect loose particles in the package, usually resulting from the assembly process. Device stress levels are derated in accordance with SPAR-RMS-PA.003 and verified by design review.

Resistors and capacitors used in the design are selected from established reliability (ER) types. Life expectancy is increased by ensuring that all allowable stress levels are derated in accordance with SPAR-RMS-PA.003. All ceramic and electrolytic capacitors are routinely subjected to radiographic inspection in accordance with the requirements of MSFC-STD-355.

Prepared: 14Oct97 by Hiltz, Michael

Supersedes: N/A

The SPA board is fabricated using Surface Mount Technology (SMT). This is a PWB assembly technology in which the components are soldered to the solder pads on the surface of the PWB. The significant advantage of this technology is to enable the parts on the board to be more densely packed, to reduce to overall volume and weight of the assembly.

The assembly process is highly automated. The parts are mounted on the boards using a computer controlled "pick and place" machine. The subsequent soldering operation is performed using a belt furnace, in which the time and temperature thermal profile that the PWB assembly is exposed to is tightly controlled and optimized to ensure proper part soldering attachment. The assembly is manufactured under documented procedures and quality controls. These controls are exercised throughout the assembly, inspection and testing of the unit. This inspection includes workmanship, component mounting, soldering, and conformal coating to ensure that it is in accordance with the NHB 5300 standards.

The SMT line used for the SPA PWB assembly has undergone a full qualification program, and assemblies produced on this line are used in other space programs.

The circuit board design has been reviewed to ensure adequate conductor width and separation and to confirm appropriate dimensions of solder pads and of component hold provisions. Parts mounting methods are controlled in accordance with MSFC-STD-154A, MSFC-STD-136 and SASD 2573751. These documents require approved mounting methods, stress relief and component security.

Test:

QUALIFICATION TESTS - The SPA is subjected to the following qualification testing:
VIBRATION: Each axis of the QM is subjected to Flight Acceptance Vibration Test (FAVT), Qualification Acceptance Vibration Test (QAVT), and Qualification Vibration Tests (QVT) in accordance with the SPA Vibration Test Procedure (826586). The level and duration for FAVT is as per Figure 6 and Table 2 of 826586; the level and duration for QAVT is as per Figure 7 and Table 2 of 826586; the level and duration for QVT is as per Figure 8 and Table of 826586. At the end of the three successive random vibration test in each axis, both directions (+/-) of each of the axis is subjected to a shock pulse test as per Figure 9 of 826586.
THERMAL/VACUUM: QM TVAC Test is in accordance with Figure 5 of the SPA TVAC Test Procedure (826588), with full Functional/Parametric Test performed at levels of +60 degrees C and -36 degrees C, and non-operating at -54 degrees C. The Qualification vacuum levels during TVAC is 1X10**-6 torr or less. The total test duration is 7 1/2 cycles. The QM SPA is subjected to a minimum of 1000 hours of life testing and 1000 power On-Off cycles.
EMC: The QM is subjected to EMC Testing (tests CE01/CE03, CE07, CS01, CS02, CS06, RE02, RS02, and RS03) in accordance with the SPA EMC test Procedure (826477) based on MIL-STD-461A.

UNIT FLIGHT ACCEPTANCE TESTS - The FM SPA is subjected to the following acceptance testing:
VIBRATION: FM Acceptance Vibration Test (AVT) in accordance with the SPA Vibration Test Procedure (826586), with level and duration as per Figure 6 and Table 2 of 826586.
THERMAL/VACUUM: FM TVAC Test is in accordance with Figure 8 of the SPA TVAC Test Procedure (826588), with levels of +49 degrees C and -25 degrees C for a duration of 1 1/2 cycles. The vacuum levels during Acceptance TVAC Test is 1X10**-5 torr or less.

JOINT SRU TESTS - The SPA is tested as part of the joints (ambient and vibration tests only). The ambient ATP for the Shoulder Joint, Elbow Joint, and Wrist Joint are as per ATP.2001, ATP.2003, and ATP.2005 respectively. The vibration test for the Shoulder Joint, and Elbow or Wrist Joint are as per ATP.2002, ATP.2004 and ATP.2006 respectively. Through wire function, continuity and electrical isolation tests are performed per TP.283.

MECHANICAL ARM REASSEMBLY - The SPA's/Joints undergo a mechanical arm integration stage where electrical checks are performed per TP.2007.

MECHANICAL ARM TESTING - The outgoing split-arm is configured on the Strongback and the Manipulator Arm Checkout is performed per ATP.1932.

FLIGHT CHECKOUT: PDRS OPS Checkout (all vehicles) JSC 16987.

Inspection:

Units are manufactured under documented quality controls. These controls are exercised throughout design procurement, planning, receiving, processing, fabrication, assembly, testing and shipping of the units. Mandatory inspection points are employed at various stages of fabrication, assembly, and test. Government source inspection is invoked at various control levels.

EEE parts inspection is performed as required by SPAR-RMS-PA.003. Each EEE part is qualified at the part level to the requirements of the applicable specification. All EEE parts are 100% screened and burned-in, as a minimum, as required by SPAR-RMS-PA.003, by the supplier. DPA is performed as required by PA.003 on a randomly selected 5% of parts, maximum 5 pieces, minimum 3 pieces for each lot number/date code of parts received. All cavity devices are subjected to 100% PIND. Wire is procured to specification MIL-W-22759 or MIL-W-81381 and inspected and tested to NASA JSCM5080 Standard Number 95A.

Receiving inspection verifies that all parts received are as identified in the procurement documents, that no physical damage has occurred to parts during shipment, that the receiving documents provide adequate traceability information and screening data clearly identifies acceptable parts.

Parts are inspected throughout manufacture and assembly as appropriate to the manufacturing stage completed. These inspections include:

Printed circuit board inspection for track separation, damage and adequacy of plated through holes, component mounting inspection for correct soldering, wire looping, strapping, etc. Operators and inspectors are trained and certified to NASA NHB 5300.4(3A-1) Standard. Conformal coating inspection for adequate processing is performed using ultraviolet light techniques. P.C. Board installation inspection includes checks for correct board installation, alignment of boards, proper connector contact mating, wire routing, strapping of wires etc. Post P.C. Board installation inspection includes cleanliness and workmanship (Spar/government rep. mandatory inspection point).

Unit Pre-Acceptance Test Inspection, which includes an audit of lower tier inspection completion, as built configuration verification to as design etc (mandatory inspection point). A unit Test Readiness Review (TRR) which includes verification of test personnel, test documents, test equipment calibration/validation status and hardware configuration is convened by QA in conjunction with Engineering, Reliability, Configuration Control, Supplier as applicable, and the government representative, prior to the start of any formal testing (Acceptance or Qualification). Unit level Acceptance Testing (ATP) includes ambient performance, thermal and vibration testing (Spar/government rep. mandatory inspection point).

Integration of unit to Joint SRU - Inspections include grounding checks, connectors for bent or pushback contacts, visual, cleanliness, interconnect wiring and power up test to the appropriate Joint Inspection Test Procedure (ITP). Joint level Pre-Acceptance Test Inspection, includes an audit of lower tier inspection completion, as built configuration verification to as design etc. Joint level Acceptance Testing (ATP) includes ambient and vibration testing (Spar/government rep. mandatory inspection point).

Mechanical Arm Reassembly - the integration of mechanical arm subassemblies to form the assembled arm. Inspections are performed at each phase of integration which includes electrical checks, through wiring checks, wiring routing, interface connectors for bent or pushback contacts etc. Mechanical Arm Testing - Strongback and flat floor ambient performance test (Spar/government rep. mandatory inspection point).

OMRSD Offline: Drive each joint in Backup. Verify backup rate signature.

OMRSD Online Installation: None.

OMRSD Online Turnaround: Command each joint in Backup. Verify audible brake click and 10 KHz tone on driven joint.

Screen Failure: A: Pass
B: Pass
C: Pass

Crew Training: The crew will be trained to always observe whether the arm is responding properly to commands. If it isn't, apply brakes.

Crew Action: Remove the drive command. Select any other mode.

Operational Effect: Loss of next redundant path results in being one failure away from inability to cradle arm. Joint will not drive in Backup. If primary modes have failed, the Backup system will not provide the capability to cradle the arm. EVA is available or arm can be jettisoned.

Mission Constraints: If Back-up is lost the mission is considered lost unless there is a flight specific exception.

Approvals:

Functional Group	Name	Position	Telephone	Date Signed	Status
Engineer	Hiltz, Michael	Systems Engineer	4534	27Feb98	Signed
Reliability	Molgaard, Lena	Reliability Engineer	4590	06Mar98	Signed
Program Management Offic	Rice, Craig	Technical Program Manager	4892	06Mar98	Signed
Subsystem Manager	Glenn, George	RMS Subsystem Manager	(281) 483-1516	24Mar98	Signed
Technical Manager	Peck, John	Technical Manager (JSC)	713-483-1284	31Mar98	Signed
SAFETY & MISSION ASSURANCE	CONN, DAVID	RMS SYSTEM ENGINEER	(281) 483-3491	30 APR 98	David C. Conn

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